



Indian Institute of Technology Kanpur
Department of Materials Science and Engineering

Enq. No.: MSE/SI/2017-18/IGSTC/sputter-targets/02

Enquiry Date: 13 December, 2017; **Closing Date:** 5 PM, 2 January, 2018

Quotations are invited for supply of sputter targets that comply with or exceed all of the specifications mentioned in **Appendix A**. The prospective suppliers are required to send quotation in two parts, each part sealed in a separate envelope. One part will be "Technical Bid" and second part will be "Financial Bid".

Terms and conditions

1. Bids from only the OEM or its authorized agent in India will be considered.
2. Bidder must provide financial-bid using the file in **appendix B**. Do not omit or rephrase any part of it. If a bidder doesn't provide pricing in the format required (given in appendix B) the corresponding bid may be rejected.
3. Following should be included along with the technical bid.
 - a) Certificate from the manufacturer of the offered sputter targets stating that 'it' is the manufacturer of **all** the offered targets.
 - b) Certification of offered purity for all the targets from the same manufacturer or reputed certifying agency.
 - c) Statement comparing the specifications of the offered targets against the specification mentioned in the present enquiry.
 - d) Copy of PO from at least three reputed academic institutes or research labs within India that the bidder participating in the present bidding process has received during 2016-2017 for supplying the sputter targets. Also, provide the contact name and e-mail of the official/laboratory at these institutes to whom the targets were supplied.
 - e) The technical-bid must carry proper certifications like agency certificate, authorization certificate, proprietary certificate etc. if applicable.
 - f) If the bidder is offering copper backing plate along with bonding services for the targets indicated in appendix **A**, then clearly mention the agency/vendor name and contact information (website, phone) who will be providing this service.
4. In the financial bid
 - g) For the indigenous parts the ex-works prices should be given, while for the imported parts the bidder must provide price on FOB, as well as CIP New Delhi basis.
Note: IIT Kanpur is registered with the Department of Scientific & Industrial Research (DSIR) for purposes of availing customs duty exemption in terms of Government Notification No. 51/96-Customs dated 23 July, 1996, and Central Excise duty exemption in terms of Government Notification No. 10/97-Central Excise dated 1 March, 1997 as amended from time to time.
 - h) For indigenous parts only, the payment term will be strictly 90% on delivery and 10% after installation and acceptance irrespective of the terms mentioned by the bidder.
 - i) The price bid must also show taxes, cost of packaging, delivery at IITK, insurance, installation and training, as applicable.

5. Validity of quotation should be at least for 75 days from the date of closing of the bid.
6. The offered product should have warranty against any manufacturing defect, or any damage during shipping and handling.
7. If the bidder has supplied sputtering-targets at IIT Kanpur during 2016 – 2017, then it must provide name of the contact person(s) corresponding to those labs/centers, complete mailing address, e-mail address, and contact phone number.
8. The Institute reserves the right to visit the site of any of the previous customers where sputtering-targets have been supplied by the bidder participating in the present bidding process and take decision based on the evaluation of the supplied product. If required the bidder should make arrangements for the site visit. The cost for the same will be borne by the indenter.
9. Bids for the targets from any dubious OEM/vendor will be rejected.
10. The technical bid will be opened on January 03, 2018 at 3PM in the Office of Stores and Purchase Section at IITK. Interested bidders are welcome to participate. No intimation will be given in the case of change of venue; however, the changed venue will be displayed on the website.
11. The date of opening of financial bid will be intimated only via email to those vendors which are selected based on the technical bids.
12. In the event of incomplete information or missing information either in the technical-bid or the financial-bid the corresponding bid will be rejected.
13. The indenter will be available for in-person discussion about the inquiry related matter on 18 December 2017, during 2 – 3PM at the address given below.

The Technical and Financial bids may be sent in sealed envelopes to:

Dr. Sarang Ingole

Room no. 412, Faculty Building

Department of Materials Sciences and Engineering

IIT Kanpur, U.P. 208016, India.

Appendix A

Essential items					
Sr. No.	Target Material	Quantity (Number of targets)	Diameter (inch)	Thickness (inch)	Minimum purity level required
1	Tin(Sn)	1	2	0.250	99.99%
2	Molybdenum (Mo)	2	2	0.250	99.99%
3	Zinc Oxide (ZnO) [intrinsic]	1	2	0.125	99.99%
4	Silicon (Si) [intrinsic]	2	2	0.125	99.99%
5	Silicon (Si) [n-type] Bulk resistivity < 0.01 Ohm-cm	2	2	0.125	99.99%
6	Silicon dioxide (SiO ₂)	2	2	0.125	99.99%
7	Germanium (Ge) [intrinsic]	2	2	0.125	99.99%
8	Tin doped indium oxide (ITO) Indium Oxide/Tin Oxide (In ₂ O ₃ /SnO ₂ 90/10 Wt%)	2	2	0.125	99.99%
Desirable items					
1	Zinc(Zn)- Tin(Sn) Alloy (Zn/Sn 50/50 atomic %)	2	2	0.250	99.99%
2	Silicon (Si) [p-type] Bulk resistivity < 0.01 Ohm-cm	2	2	0.125	99.99%

Note:

- (1) The targets mentioned at the serial numbers 3 to 8 in the above table in Essential category and at serial no. 2 in Desirable category have to be bonded to copper backing plate using silver-filled epoxy. Indicate in the technical-bid whether this service will be provided, and mention the associated cost for Cu-backing plate and bonding service in the financial bid.
- (2) For those targets where quantity required has been indicated as **2**, we may place order for only one target depending on the budget.

-----End of Appendix A-----

Appendix B (Price Bid)

Sr. No.	Target Material	Diameter (inch)	Unit (one target)	Price per unit	No. of units	Total
Essentials						
1	Tin(Sn)	2	1		1	
2	Molybdenum (Mo)	2	1		2	
3	Zinc Oxide (ZnO)	2	1		1	
4	Silicon (Si) [intrinsic]	2	1		2	
5	Silicon (Si) [n-type] Bulk resistivity < 0.01 Ohm-cm	2	1		2	
6	Silicon di-Oxide (SiO ₂)	2	1		2	
7	Germanium (Ge) [intrinsic]	2	1		2	
8	ITO Indium Oxide/Tin Oxide (In ₂ O ₃ /SnO ₂ 90/10 Wt%)	2	1		2	
Desirables						
1	Zinc(Zn)- Tin(Sn) Alloy (Zn/Sn 50/50 atomic %)	2	1		2	
2	Silicon (Si) [p-type] Bulk resistivity < 0.01 Ohm-cm	2	1		2	
				Sub-total (A)		
a	Target bonding service including copper backing plate		Each target		13	
b				FOB charges		
c				Tax		
d				Packaging		
e				Insurance		
f				Delivery at IITK		
Mention below any other costs						
g						
h						
i						
				Sub-total (B)		
				Grand Total (A+B)		

Bidder may use additional sheets if required.

-----End of Appendix B-----